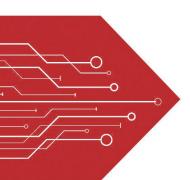
## MSKSEMI















**ESD** 

TVS

TSS

MOV

**GDT** 

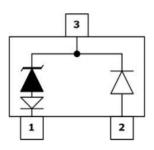
**PLED** 

# Brodnet data speet

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SOT-23

#### **Features**

- Ultra low leakage: nA level
- Operating voltage: 2.8V
- Low clamping voltage
- Complies with following standards:
  - IEC 61000-4-2 (ESD) immunity test

Air discharge: ±15kV

Contact discharge: ±8kV

- IEC61000-4-4 (EFT) 40A (5/50ns)
- IEC61000-4-5 (Lightning) 24A (8/20µs)
- **RoHS Compliant**

#### **Applications**

- USB 2.0 power and data line
- Set-top box and digital TV
- Digital video interface (DVI)
- **Notebook Computers**
- SIM Ports
- 10/100 Ethernet

#### **Mechanical Characteristics**

Package: SOT-23

Lead Finish: Lead Free

UL Flammability Classification Rating 94V-0

Quantity Per Reel:3,000pcs

Reel Size:7inch

#### **Absolute Maximum Ratings**(Tamb=25°C unless otherwise specified)

Parameter	Symbol	Value	Unit	
Peak Pulse Power (8/20µs)	Ррр	400	W	
ESD per IEC 61000-4-2 (Air)	Vesd	±15	Kv	
ESD per IEC 61000-4-2 (Contact)	<b>V</b> ESD	±8		
Operating Temperature Range	TJ	-55 to +125	$^{\circ}$	
Storage Temperature Range	Тѕтл	-55 to +150	$^{\circ}$	



### Electrical Characteristics (TA=25°C unless otherwise specified)

		$V_{RWM}$	V <sub>BR</sub>	Iτ	V <sub>BR</sub> I <sub>T</sub>	V <sub>BR</sub> I <sub>T</sub>	Vc	Vc	V	'c	IR	C
P/N	Marking	(V)	(V)	(mA)	@1A	@1A	(Max)	(@A)	μA (Max)	(Pf) (Typ.)		
SLVU2.8-MS	U2.8	2.8	3	1	7	15	24	1	5			

#### **Characteristic Curves**

Fig1. 8/20 µs Pulse Waveform

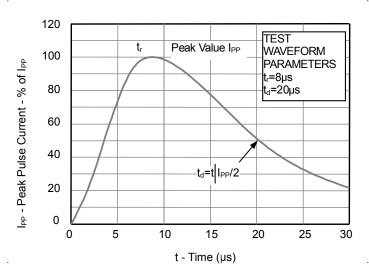


Fig2. ESD Pulse Waveform (according to IEC 61000-4-2)

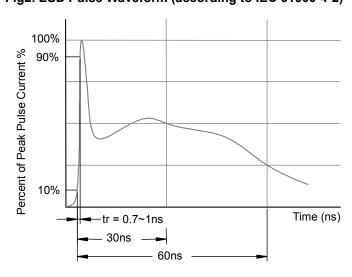
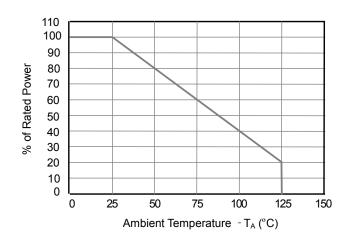


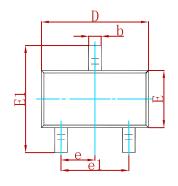
Fig3. Power Derating Curve

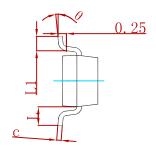


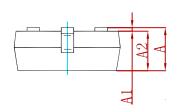




#### **PACKAGE MECHANICAL DATA**

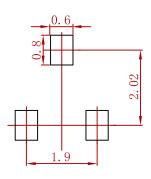






Symbol	Dimensions	In Millimeters	Dimensions In Inches		
Symbol	Min	Max	Min	Max	
Α	0.900	1.150	0.035	0.045	
A1	0.000	0.100	0.000	0.004	
A2	0.900	1.050	0.035	0.041	
b	0.300	0.500	0.012	0.020	
С	0.080	0.150	0.003	0.006	
D	2.800	3.000	0.110	0.118	
E	1.200	1.400	0.047	0.055	
E1	2.250	2.550	0.089	0.100	
е	0.950 TYP		0.037 TYP		
e1	1.800	2.000	0.071	0.079	
L	0.550 REF		0.022 REF		
L1	0.300	0.500	0.012	0.020	
θ	0°	8°	0°	8°	

#### **Suggested Pad Layout**



- 1.Controlling dimension:in millimeters.2.General tolerance:± 0.05mm.3.The pad layout is for reference purposes only.

#### **REEL SPECIFICATION**

P/N	PKG	QTY
SLVU2.8-MS	SOT-23	3000



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